

Title (en)

DEVICE AND METHOD FOR BENDING, AND BENDING DIE

Title (de)

VORRICHTUNG UND VERFAHREN ZUM BIEGEN UND BIEGEWERKZEUG

Title (fr)

DISPOSITIF ET PROCEDE DE PLIAGE, ET OUTIL DE PLIAGE

Publication

**EP 1658908 A4 20090121 (EN)**

Application

**EP 04746554 A 20040622**

Priority

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- JP 2003177586 A 20030623
- JP 2004151082 A 20040520
- JP 2004166512 A 20040604

Abstract (en)

[origin: EP1658908A1] In a bending apparatus which moves one of upper and lower tables (9, 10), and performs bending on a workpiece (W) by tools (P, D) attached to the upper and lower tables (9, 10), a tool group including a plurality of split tools is transferred to the upper and lower table (9, 10), a plurality of process stations are formed by splitting the transferred tool into a plurality of tool groups based on automatically or manually determined tool-layout information, and then bending is carried out.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

- [AX] EP 1160024 A1 20011205 - AMADA CO LTD [JP] & WO 0041824 A1 20000720 - AMADA CO LTD [JP], et al
- See references of WO 2004112981A1

Cited by

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